SDLS036 - DECEMBER 1983 - REVISED MARCH 1988

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

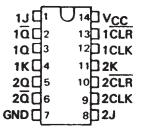
#### description

The '107 contain two independent J-K flip-flops with individual J-K, clock, and direct clear inputs. The '107 is a positive pulse-triggered flip-flop. The J-K input data is loaded into the master while the clock is high and transferred to the slave and the outputs on the high-to-low clock transistion. For these devices the J and K inputs must be stable while the clock is high.

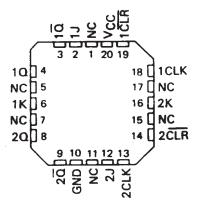
The 'LS107A contain two independent negative-edge-triggered flip-flops. The J and K inputs must be stable prior to the high-to-low clock transition for predictable operation. When the clear is low, it overrides the clock and data inputs forcing the Q output low and the  $\overline{\mathbf{Q}}$  output high.

The SN54107 and the SN54LS107A are characterized for operation over the full military temperature range of -55 °C to 125 °C. The SN74107 and the SN74LS107A are characterized for operation from 0 °C to 70 °C.

SN54107, SN54LS107A . . . J PACKAGE SN74107 . . . N PACKAGE SN74LS107A . . . D OR N PACKAGE (TOP VIEW)



SN54LS107A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

'107
FUNCTION TABLE

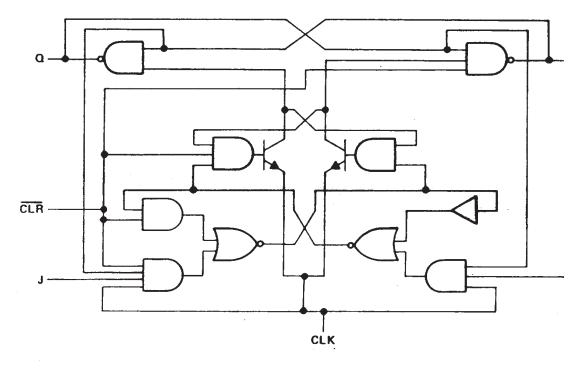
	INPU	OUTPUTS			
CLR	CLK	J	K	Q	ā
L	×	Х	Х	L	Н
н	ır	L	L	$\alpha_0$	$\bar{a}_0$
н	v	Н	L	н	L
н	. 1	i.	н	L	Н
н	л	Н	н	TOG	GLE

'LS 107A FUNCTION TABLE

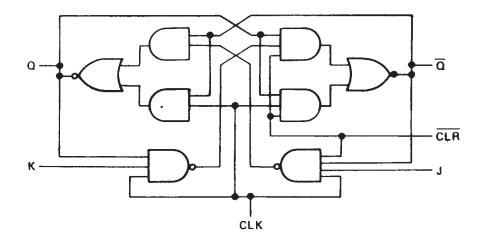
	INPU	OUTPUTS			
CLR	CLK	J	κ	α	₫
L	×	Х	Х	L	H
н	1	L	L	$\sigma_0$	$\bar{a}_0$
н	4	Н	L	н	L
н	1	L	Н	L	н
н⊦	4	H.	Н	TOG	GLE
н	Н	Х	X	△0	$\overline{a}_0$



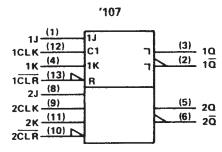
### logic diagrams (positive logic)

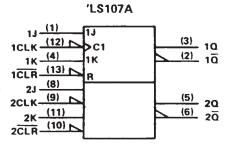


'LS107A



#### logic symbols†

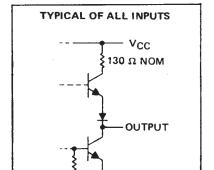




<sup>†</sup>These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, J, and N packages.

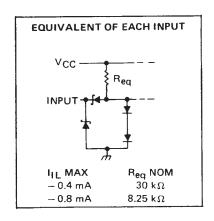
#### schematic of inputs and outputs

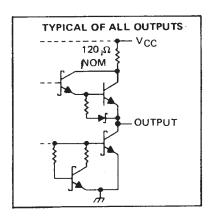
**EQUIVALENT OF EACH INPUT** V<sub>C</sub>C INPUT IIL MAX R<sub>eq</sub> NOM - 1.6 mA 4kΩ - 3.2 mA  $2 k\Omega$ 



#### 'LS107A

107





### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

5	Supply voltage, VCC (see Note 1)	/ V
1	Input voltage: '107	5.5 V
	1 5107Δ	7 V
(	Operating free-air temperature range: SN54'	55°C to 125°C
	SN74'	U C to /U C
5	Storage temperature range	– 65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.



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#### recommended operating conditions

				SN54107		SN74107			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	ייאט ך
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage					2			٧
VIL	Low-level input voltage			0.8			8.0	٧	
ЮН	High-level output current			- 0.4			- 0.4	mA	
IOL	Low-level output current				16			16	mA
		CLK high	20			20			
tw	Pulse duration	CLK low	47			47			ns
		CLR low	25			25			
t <sub>su</sub>	Input setup time before CLK1		0			0			ns
t <sub>h</sub>	Input hold time-data after CLK1		0			0			ns
TA	Operating free-air temperature		- 55		125	0		70	°C

#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DAG.	RAMETER	TEST CONDITIONS†				SN54107			SN74107			
FAR	AMETER		TEST CONDITION	ONS.	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT	
$v_{iK}$		V <sub>CC</sub> = MIN,	I <sub>1</sub> = - 12 mA				- 1.5			<b>– 1.5</b>	V	
V <sub>OH</sub>		V <sub>CC</sub> = MIN,		V <sub>IL</sub> = 0.8 V,	2.4	3.4		2.4	3.4		V	
VOL		V <sub>CC</sub> = MIN, I <sub>OL</sub> = 16 mA	V <sub>IH</sub> = 2 V,	V <sub>1</sub> L = 0.8 V,		0.2	0.4		0.2	0.4	٧	
l <sub>l</sub>		V <sub>CC</sub> = MAX,	V <sub>1</sub> = 5.5 V				1			1	mA	
1	J or K	VMAY	V1 = 2.4 V				40			40		
ΊΗ	All other	V <sub>CC</sub> = MAX,	V   = 2.4 V				80			80	μΑ	
1	J or K	VMAY	V =0.4 V				- 1.6			- 1.6		
ΊL	All other	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 0.4 V			- 3.2		- 3.2	mA			
los §		V <sub>CC</sub> = MAX			- 20		- 57	- 18		- 57	mA	
lcc1		V <sub>CC</sub> = MAX,	See Note 2			10	20		10	20	mA	

<sup>†</sup>For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: With all outputs open,  $I_{CC}$  is measured with the Q and  $\overline{Q}$  outputs high in turn. At the time of measurement, the clock input is grounded.

### switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f <sub>max</sub>				15	20		MHz
<sup>†</sup> PLH	CLR	ā			16	25	ns
<sup>t</sup> PHL	CLA	α	$R_{\perp} = 400 \Omega$ , $C_{\perp} = 15 pF$		25	40	ns
<sup>t</sup> PLH	CLK	Q or $\overline{\Omega}$			16	25	ns
<sup>t</sup> PHL	CLK	u or u			25	40	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



 $<sup>^{\</sup>ddagger}$ All typical values are at  $V_{CC}$  = 5 V,  $T_{A}$  = 25 ° C.

Not more than one output should be shorted at a time.

<sup>¶</sup>Average per flip-flop.

#### recommended operating conditions

			SN54LS107A		07A	SN74LS107A			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	UNII
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
ViH	High-level input voltage	High-level input voltage				2			V
VIL	Low-level input voltage			0.7			8.0	V	
10H	High-level output current			- 0.4			- 0.4	mA	
†OL	Low-level output current			4			8	mA	
fclock	Clock frequency		0		30	0		30	MHz
	Dulan shared an	CLK high	20			20			
tw	Pulse duration	CLR low	25		;	25			ns
	0	data high or low	20			20			
<sup>t</sup> su	Setup time before CLK #	CLR inactive	25			25			ns
th	Hold time-data after CLK↓		0			0			ns
TA	Operating free-air temperature		- 55		125	0		70	°C

#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

			EST CONDITIO	ust	SN	154LS10	7A	SN	174LS10	)7A	UNIT
PARAMETER		TEST CONDITIONS.			MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNII
VIK		V <sub>CC</sub> = MIN,					- 1.5			<b>– 1.5</b>	· V
Vон		V <sub>CC</sub> = MIN, I <sub>OH</sub> = 0.4 mA	V <sub>IH</sub> = 2 V,	VIL = MAX,	2.5	3.4		2.7	3.4		٧
.,		V <sub>CC</sub> = MIN, I <sub>OL</sub> = 4 mA	VIL = MAX,	V <sub>IH</sub> = 2 V,		0.25	0.4		0.25	0.4	V
VOL		V <sub>CC</sub> = MIN, I <sub>OL</sub> = 8 mA	VCC = MIN, VIL = MAX, VIH						0.35	0.5	
	J or K						0.1			0.1	
1	CLR	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 7 V				0.3			0.3	mA
	CLK						0.4			0.4	
• • • •	J or K						20			20	
ЧН	CLR	V <sub>CC</sub> = MAX,	V1 = 2.7 V	V <sub>1</sub> = 2.7 V			60			60	μΑ
	CLK	]					80			80	
	J or K					- 0.4				- 0.4	mA
HL	CLR or CLK	VCC = MAX,	CC = MAX, V <sub>I</sub> = 0.4 V				- 0.8			- 0.8	100
los§		V <sub>CC</sub> = MAX,	See Note 4		- 20		- 100	- 20		- 100	mA
Icc (	Total)	V <sub>CC</sub> = MAX,	See Note 2			4	6		4	6	mA

<sup>†</sup>For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

## switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS		MIN	TYP	MAX	UNIT
fmax			,		30	45		MHz
tPLH	<del></del>	^ =	$R_L = 2 k\Omega$ ,	C <sub>L</sub> = 15 pF		15	20	ns
tPHL	CLR or CLK	Q or Q				15	20	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



 $<sup>\</sup>ddagger$  All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

<sup>§</sup> Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

NOTE 2: With all outputs open,  $I_{CC}$  is measured with the Q and  $\overline{Q}$ , outputs high in turn. At the time of measurement, the clock input is grounded.

NOTE 4: For certain devices where state commutation can be caused by shorting an output to ground, an equivalent test may be performed with V<sub>O</sub> = 2.25 V and 2.125 V for the 54 family and the 74 family, respectively, with the minimum and maximum limits reduced to one half of their stated values.







### **PACKAGING INFORMATION**

O	rderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
JM	38510/00203BCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
	SN54107J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
	SN54107J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
	SN74107N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
	SN74107N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
	SN74107N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
	SN74107N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
	SN74LS107AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
	SN74LS107AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SI	N74LS107ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SI	N74LS107ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
S	N74LS107ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
S	N74LS107ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN	I74LS107ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN	I74LS107ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
	SN74LS107AN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
	SN74LS107AN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
S	N74LS107AN3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
S	N74LS107AN3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SI	N74LS107ANE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SI	N74LS107ANE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SI	N74LS107ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SI	N74LS107ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN	74LS107ANSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN	74LS107ANSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
	SNJ54107J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
	SNJ54107J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC

(1) The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.



#### PACKAGE OPTION ADDENDUM

17-Oct-2005

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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#### 14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

## N (R-PDIP-T\*\*)

### PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



# D (R-PDSO-G14)

### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AB.



### **MECHANICAL DATA**

### NS (R-PDSO-G\*\*)

## 14-PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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